



2827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Kevin K-T. CHUNG

Appl. Serial No. 09/578,583

Filed: May 25, 2000

For: **SOLDERABLE FLEXIBLE ADHESIVE INTERPOSER AS FOR AN ELECTRONIC PACKAGE, AND METHOD FOR MAKING SAME:**

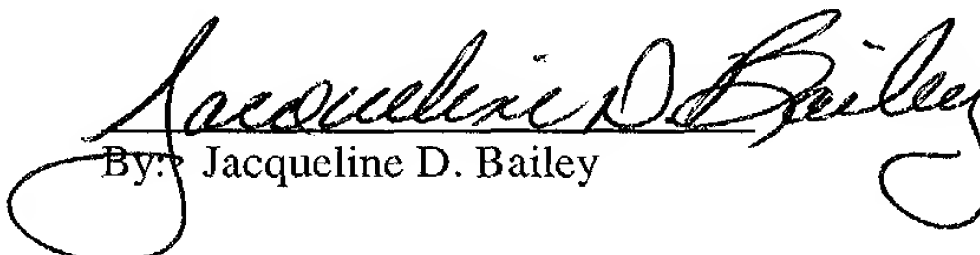
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: Art Unit: 2827
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: Examiner: Tuan T. Dinh
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: Confirmation No. 7346
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March 20, 2003
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By: Jacqueline D. Bailey

RESPONSE TO OFFICE ACTION UNDER 37 C.F.R. §1.111

This is a Response to the Office Letter mailed December 31, 2003 in the above-captioned Application for which the three-month shortened statutory period for response expires March 31, 2003.

In the Claims:

Please rewrite claims 16, 23 and 31 to read as follows:

16. (Amended) A solderable flexible adhesive interposer comprising:
- at least one layer of flexible dielectric adhesive having a modulus of elasticity less than about 35,000 kg/cm² (about 500,000 psi),
 - a plurality of conductive vias through said layer of flexible dielectric adhesive, said plurality of conductive vias being of a flexible electrically conductive adhesive having a modulus of elasticity less than about 35,000 kg/cm² (about 500,000 psi) and being in a pattern adapted for connection to contacts of an electronic device or a substrate, and